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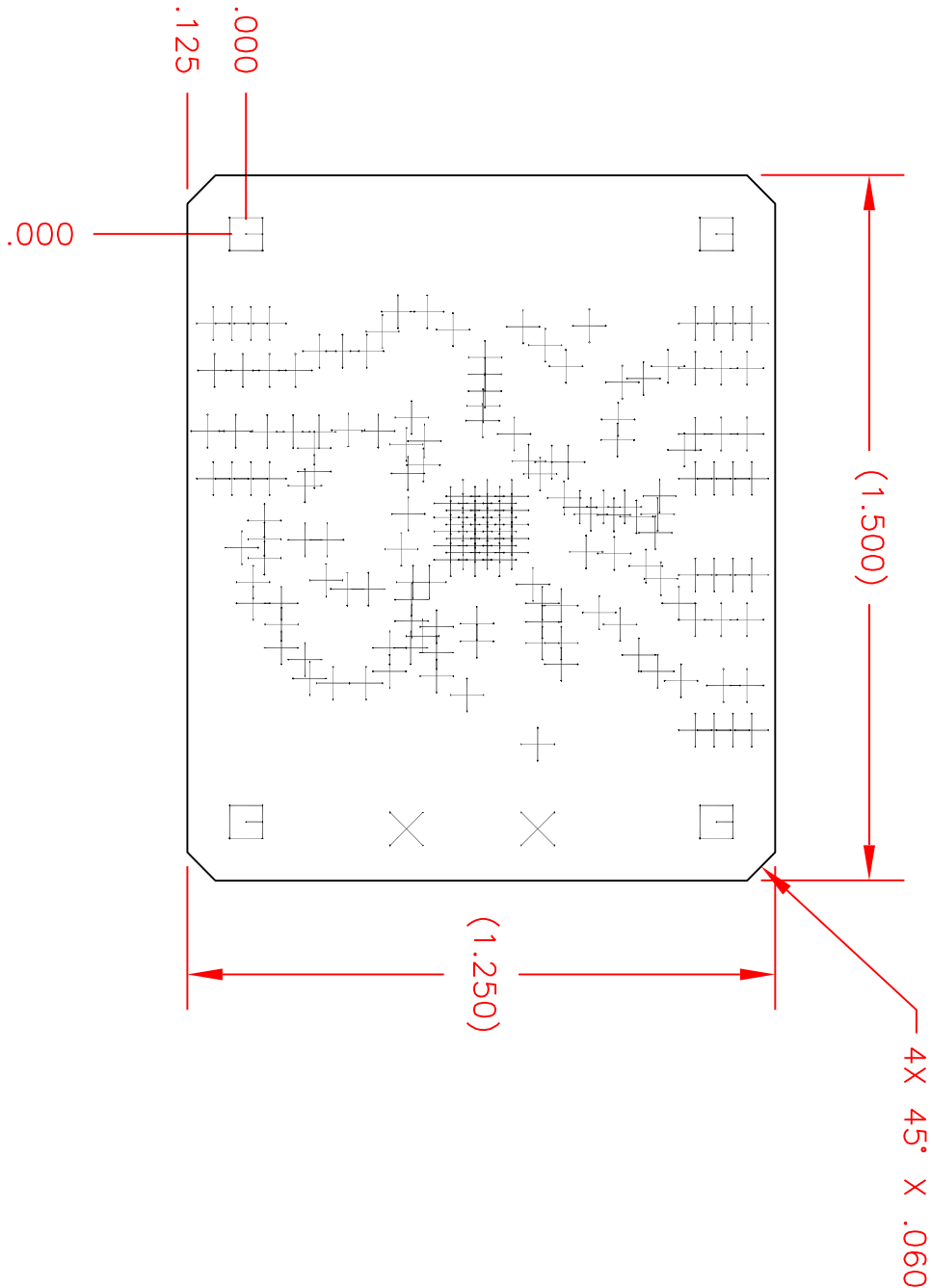
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REVISION		ECO	DATE	BY/APPRO
REV	DESCRIPTION			
1	VARIOUS CHANGES		8-19-03	TAP/RLR
2	ADD ATTN PADS		12-2-03	TAP/RLR
3	UPDATED TITLE		6-6-05	TAP/RLR

NOTES UNLESS OTHERWISE SPECIFIED:

1. FABRICATE IAW IPC-6012, CLASS 2, CURRENT REVISION.
2. BOARD SHALL MEET THE INSPECTION CRITERIA OF IPC-A-600 CLASS 2, CURRENT REVISION.
3. USE ARTWORK 452788AW REV 3.
- 4 MATERIAL: FR4. SEE LAYER STACK-UP BELOW.
- 5 FINISHED WEIGHT OF ALL COPPER LAYERS SHALL BE 1 OZ. PER SQUARE FOOT NOMINAL.
6. DESMEAR HOLES AND VIAS.
- 7 FINISH: HOT-AIR LEVEL TIN-LEAD (HASL).
8. SILKSCREEN COMPONENT SIDE ONLY WITH NONCONDUCTIVE EPOXY INK. COLOR SHALL BE A CONTRASTING INK WITH RESPECT TO SOLDERMASK COLOR. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. REMOVE EPOXY INK FROM SOLDER LANDS.
9. APPLY SOLDERMASK OVER BARE COPPER (SMOBC) IAW IPC-SM-840, BOTH SIDES, USING LPI, COLOR CLEAR OR GREEN. SOLDERMASK OVER VIAS IS NOT ACCEPTABLE.
10. TANGENCY IS ACCEPTABLE.
11. REMOVAL OF NON-FUNCTIONAL PADS ON INTERNAL LAYERS IS ACCEPTABLE.
- 12 SUPPLIER LOGO AND LOT NUMBER/DATE CODE SHALL ONLY BE SILKSCREENED WITH NON-CONDUCTIVE EPOXY INK IN APPROX. LOCATION SHOWN.
- 13 MARK ARTWORK 453104AW, CURRENT REV LEVEL APPROX. WHERE SHOWN.
14. ALL ROUTING ARE INDICATED BY HATCHED AREAS.
- 15 SCORING PROCESS TO FOLLOW DETAIL "A" ( SEE SHEET 2). CIRCUIT FABRICATOR TO BREAK ONE SUB-PANEL FROM EACH LOT TO ENSURE PROPER SCORING ACHIEVED.
- 16 A MAXIMUM OF TWO (2) X-OUT ARE ALLOWED PER SUB-PANEL.

COMPONENT SIDE



4 LAYER  
CROSS SECTION  
FILM SET

5

LAYER 1 - COMP SIDE  
LAYER 2 - GND PLANE  
LAYER 3 - INTERNAL SIGNAL  
LAYER 4 - BOTTOM SIDE

4 LAYER  
CROSS SECTION  
DIMENSIONAL TOLERANCE

PREPREG .014 ±.002  
CORE  
PREPREG .014

.062 ±.006

HOLE SCHEDULE (ALL PLATED THRU DIAMETERS ARE AFTER PLATING)				
SYM	DESCRIPTION	PLATED THRU	QTY	
+	Ø.010 +.003/-.010 THRU	YES	173	
X	Ø.055 +.001/-.003 THRU	YES	2	
□	Ø.102 ±.003 THRU	YES	4	

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OSIZE 00/08/16 8

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452788PC